TECHNOLUTIONS solutions for sci-tech

SYMPOSIUM PROGRAM

Thin film engineering for photovoltaics, photonics and optoelectronics

Wednesday 16.02.2022

TIME	TOPIC	LECTURER	INSTITUTION
8:30 - 9:15	Registration	-	-
9:15 - 9:30	Inauguration	Tomasz Szablewski Prof. Maria Kamińska	TECHNOLUTIONS, UNIWERSYTET WARSZAWSKI
9:30 - 10:15	Spin coating – an introduction to a common methodology and its hidden difficulties	Tom Trowles	LAURELL TECHNOLOGIES CORPORATION
10:15 - 10:45	ALD features and popular applications – LED, OLED, Sensors, displays, photovoltaics	Kari Koski	BENEQ OY
10:45 - 11:00	Wykorzystanie technologii wzrostu cienkich warstw w ogniwach PV III gen	Paweł Kwaśnicki	ML SYSTEM S.A.
11:00 - 11:20	Laboratory scale physical vapour deposition processes	Colin Moorhouse	MOORFIELD NANOTECHNOLOGY LIMITED
11:20 - 12:00	Coffee Break	-	-
12:00 - 12:30	Plasma Enhanced Chemical Vapour Deposition. CCP vs ICP PECVD	Andreas Stamm	OXFORD INSTRUMENTS
12:30 - 13:00	Thin Film & Solar Energy applications: from Lab Scale to Large Area	Paola Santilli	KENOSISTEC SRL
13:00 - 13:45	To be defined	Andrzej Miszczuk	ROLTEC SP. Z O. O.
13:45 - 14:40	Lunch	-	-
14:40 - 15:00	2D materials using CVD Technology	Colin Moorhouse	MOORFIELD NANOTECHNOLOGY LIMITED
15:00 - 15:30	Laser litography for microelectronic devices	Nils Goedecke	HEIDELBERG INSTRUMENTS MIKROTECHNIK GmbH
15:30 - 17:00	Poster Session	-	-
19:30 - 00:00	Dinner	-	-

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Thursday 17.02.2022

TIME	TOPIC	LECTURER	INSTITUTION
9:00 - 9:30	Controlled etching at very low rates and Atomic Layer Etching for Nanoscale application	Andreas Stamm	OXFORD INSTRUMENTS
9:30 - 10:15	Wet chemical processing – a better method, and the benefits it offers	Tom Trowles	LAURELL TECHNOLOGIES CORPORATION
10:15 - 10:45	3D Micro-fabrication and multiphoton polymerization	Titas Gertus	FEMTIKA
10:45 - 11:10	High sensitivity parallel dipole line hall measurement system	Christophe Defranoux	SEMILAB
11:10 - 11:30	Coffee Break	-	-
11:30 - 12:15	Profilometry Technologies for thin-film characterisation	Daniel Mandic	KLA INSTRUMENTS GROUP
12:15 - 12:40	Latest development of spectroscopic Ellipsometry for optoelectronic devices	Christophe Defranoux	SEMILAB
12:40 - 13:25	Characterization of thin films by 3D profilometry and scratch testing in semiconductor industries	Philippe Kempe	RTEC-INSTRUMENTS SA
13:25-14:30	Lunch	-	-
14:30 - 15:15	High lateral resolution and microscopic mapping - thin film characterisation by Imaging Ellipsometry Mechanical	Peter Thiensen	ACCURION GmbH
15:15 - 15:45	4D real time imaging - Holographic microscopy	Patryk Nienałtowski	POLITECHNIKA WARSZAWSKA LYNCÉE TEC
15:45 - 16:30	Thin-Film thickness measurements using optical and electrical technologies	Daniel Mandic	KLA INSTRUMENTS GROUP
16:30 - 16:55	Electrical metrologies in semiconductor area	Christophe Defranoux	SEMILAB
16:55 - 17:15	The End / Certificates	Tomasz Szablewski	TECHNOLUTIONS